

# MUN2236, MMUN2236L, MUN5236, DTC115EE, DTC115EM3

## Digital Transistors (BRT) R1 = 100 kΩ, R2 = 100 kΩ

### NPN Transistors with Monolithic Bias Resistor Network

This series of digital transistors is designed to replace a single device and its external resistor bias network. The Bias Resistor Transistor (BRT) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. The BRT eliminates these individual components by integrating them into a single device. The use of a BRT can reduce both system cost and board space.

#### Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

| Rating                         | Symbol               | Max | Unit |
|--------------------------------|----------------------|-----|------|
| Collector-Base Voltage         | V <sub>CBO</sub>     | 50  | Vdc  |
| Collector-Emitter Voltage      | V <sub>CEO</sub>     | 50  | Vdc  |
| Collector Current - Continuous | I <sub>C</sub>       | 100 | mAdc |
| Input Forward Voltage          | V <sub>IN(fwd)</sub> | 40  | Vdc  |
| Input Reverse Voltage          | V <sub>IN(rev)</sub> | 10  | Vdc  |

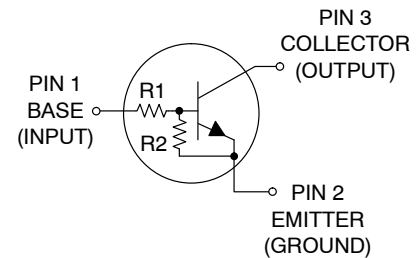
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



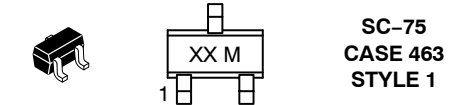
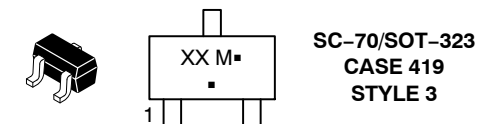
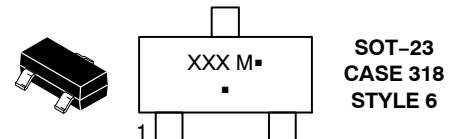
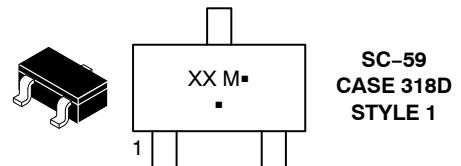
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#### PIN CONNECTIONS



#### MARKING DIAGRAMS



XXX = Specific Device Code  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

#### ORDERING INFORMATION

See detailed ordering, marking, and shipping information in the package dimensions section on page 2 of this data sheet.

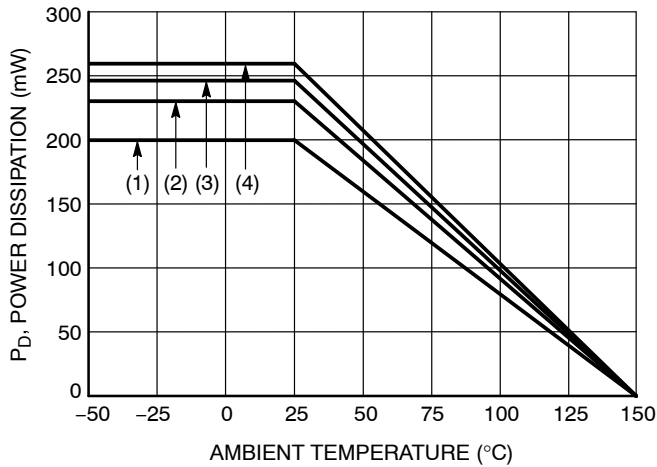
# MUN2236, MMUN2236L, MUN5236, DTC115EE, DTC115EM3

**Table 1. ORDERING INFORMATION**

| Device                         | Part Marking | Package                    | Shipping†          |
|--------------------------------|--------------|----------------------------|--------------------|
| MUN2236T1G, NSVMUN2236T1G*     | 8N           | SC-59<br>(Pb-Free)         | 3000 / Tape & Reel |
| MMUN2236LT1G, NSVMMUN2236LT1G* | AA5          | SOT-23<br>(Pb-Free)        | 3000 / Tape & Reel |
| MUN5236T1G, NSVMUN5236T1G*     | 8N           | SC-70/SOT-323<br>(Pb-Free) | 3000 / Tape & Reel |
| DTC115EET1G                    | 8N           | SC-75<br>(Pb-Free)         | 3000 / Tape & Reel |
| DTC115EM3T5G                   | 8N           | SOT-723<br>(Pb-Free)       | 8000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.



- (1) SC-75 and SC-70/SOT323; Minimum Pad
- (2) SC-59; Minimum Pad
- (3) SOT-23; Minimum Pad
- (4) SOT-723; Minimum Pad

**Figure 1. Derating Curve**

MUN2236, MMUN2236L, MUN5236, DTC115EE, DTC115EM3

Table 2. THERMAL CHARACTERISTICS

| Characteristic  | Symbol  | Max                      | Unit                       |
|---|---|--------------------------|----------------------------|
| <b>THERMAL CHARACTERISTICS (SC-59) (MUN2236)</b>  |   |                          |                            |
| Total Device Dissipation<br>$T_A = 25^\circ\text{C}$<br>Derate above $25^\circ\text{C}$ | (Note 1)<br>(Note 2)<br>(Note 1)<br>(Note 2)<br>$P_D$ | 230<br>338<br>1.8<br>2.7 | mW<br>mW/ $^\circ\text{C}$ |
| Thermal Resistance,<br>Junction to Ambient  | (Note 1)<br>(Note 2)<br>$R_{\theta JA}$               | 540<br>370               | $^\circ\text{C}/\text{W}$  |
| Thermal Resistance,<br>Junction to Lead   | (Note 1)<br>(Note 2)<br>$R_{\theta JL}$               | 264<br>287               | $^\circ\text{C}/\text{W}$  |
| Junction and Storage Temperature Range  | $T_J, T_{stg}$  | -55 to +150              | $^\circ\text{C}$           |

**THERMAL CHARACTERISTICS (SOT-23) (MMUN2236L)**

|   |   |                          |                            |
|---|---|--------------------------|----------------------------|
| Total Device Dissipation<br>$T_A = 25^\circ\text{C}$<br>Derate above $25^\circ\text{C}$ | (Note 1)<br>(Note 2)<br>(Note 1)<br>(Note 2)<br>$P_D$ | 246<br>400<br>2.0<br>3.2 | mW<br>mW/ $^\circ\text{C}$ |
| Thermal Resistance,<br>Junction to Ambient  | (Note 1)<br>(Note 2)<br>$R_{\theta JA}$               | 508<br>311               | $^\circ\text{C}/\text{W}$  |
| Thermal Resistance,<br>Junction to Lead   | (Note 1)<br>(Note 2)<br>$R_{\theta JL}$               | 174<br>208               | $^\circ\text{C}/\text{W}$  |
| Junction and Storage Temperature Range  | $T_J, T_{stg}$  | -55 to +150              | $^\circ\text{C}$           |

**THERMAL CHARACTERISTICS (SC-70/SOT-323) (MUN5236)**

|   |   |                          |                            |
|---|---|--------------------------|----------------------------|
| Total Device Dissipation<br>$T_A = 25^\circ\text{C}$<br>Derate above $25^\circ\text{C}$ | (Note 1)<br>(Note 2)<br>(Note 1)<br>(Note 2)<br>$P_D$ | 202<br>310<br>1.6<br>2.5 | mW<br>mW/ $^\circ\text{C}$ |
| Thermal Resistance,<br>Junction to Ambient  | (Note 1)<br>(Note 2)<br>$R_{\theta JA}$               | 618<br>403               | $^\circ\text{C}/\text{W}$  |
| Thermal Resistance,<br>Junction to Lead   | (Note 1)<br>(Note 2)<br>$R_{\theta JL}$               | 280<br>332               | $^\circ\text{C}/\text{W}$  |
| Junction and Storage Temperature Range  | $T_J, T_{stg}$  | -55 to +150              | $^\circ\text{C}$           |

**THERMAL CHARACTERISTICS (SC-75) (DTC115EE)**

|   |   |                          |                            |
|---|---|--------------------------|----------------------------|
| Total Device Dissipation<br>$T_A = 25^\circ\text{C}$<br>Derate above $25^\circ\text{C}$ | (Note 1)<br>(Note 2)<br>(Note 1)<br>(Note 2)<br>$P_D$ | 200<br>300<br>1.6<br>2.4 | mW<br>mW/ $^\circ\text{C}$ |
| Thermal Resistance,<br>Junction to Ambient  | (Note 1)<br>(Note 2)<br>$R_{\theta JA}$               | 600<br>400               | $^\circ\text{C}/\text{W}$  |
| Junction and Storage Temperature Range  | $T_J, T_{stg}$  | -55 to +150              | $^\circ\text{C}$           |

**THERMAL CHARACTERISTICS (SOT-723) (DTC115EM3)**

|   |   |                          |                            |
|---|---|--------------------------|----------------------------|
| Total Device Dissipation<br>$T_A = 25^\circ\text{C}$<br>Derate above $25^\circ\text{C}$ | (Note 1)<br>(Note 2)<br>(Note 1)<br>(Note 2)<br>$P_D$ | 260<br>600<br>2.0<br>4.8 | mW<br>mW/ $^\circ\text{C}$ |
| Thermal Resistance,<br>Junction to Ambient  | (Note 1)<br>(Note 2)<br>$R_{\theta JA}$               | 480<br>205               | $^\circ\text{C}/\text{W}$  |
| Junction and Storage Temperature Range  | $T_J, T_{stg}$  | -55 to +150              | $^\circ\text{C}$           |

- FR-4 @ Minimum Pad.
- FR-4 @ 1.0 x 1.0 Inch Pad.

# MUN2236, MMUN2236L, MUN5236, DTC115EE, DTC115EM3

**Table 3. ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

| Characteristic   | Symbol        | Min | Typ | Max  | Unit       |
|--|---------------|-----|-----|------|------------|
| <b>OFF CHARACTERISTICS</b>   |               |     |     |      |            |
| Collector-Base Cutoff Current<br>( $V_{CB} = 50\text{ V}$ , $I_E = 0$ )                                  | $I_{CBO}$     | -   | -   | 100  | nAdc       |
| Collector-Emitter Cutoff Current<br>( $V_{CE} = 50\text{ V}$ , $I_B = 0$ )                               | $I_{CEO}$     | -   | -   | 500  | nAdc       |
| Emitter-Base Cutoff Current<br>( $V_{EB} = 6.0\text{ V}$ , $I_C = 0$ )                                   | $I_{EBO}$     | -   | -   | 0.05 | mAdc       |
| Collector-Base Breakdown Voltage<br>( $I_C = 10\ \mu\text{A}$ , $I_E = 0$ )                              | $V_{(BR)CBO}$ | 50  | -   | -    | Vdc        |
| Collector-Emitter Breakdown Voltage (Note 3)<br>( $I_C = 2.0\text{ mA}$ , $I_B = 0$ )                    | $V_{(BR)CEO}$ | 50  | -   | -    | Vdc        |
| <b>ON CHARACTERISTICS</b>  |               |     |     |      |            |
| DC Current Gain (Note 3)<br>( $I_C = 5.0\text{ mA}$ , $V_{CE} = 10\text{ V}$ )                           | $h_{FE}$      | 80  | 150 | -    |            |
| Collector-Emitter Saturation Voltage (Note 3)<br>( $I_C = 10\text{ mA}$ , $I_B = 0.3\text{ mA}$ )        | $V_{CE(sat)}$ | -   | -   | 0.25 | Vdc        |
| Input Voltage (off)<br>( $V_{CE} = 5.0\text{ V}$ , $I_C = 100\ \mu\text{A}$ )                            | $V_{i(off)}$  | -   | 1.2 | 0.5  | Vdc        |
| Input Voltage (on)<br>( $V_{CE} = 0.3\text{ V}$ , $I_C = 1.0\text{ mA}$ )                                | $V_{i(on)}$   | 3.0 | 1.7 | -    | Vdc        |
| Output Voltage (on)<br>( $V_{CC} = 5.0\text{ V}$ , $V_B = 5.5\text{ V}$ , $R_L = 1.0\text{ k}\Omega$ )   | $V_{OL}$      | -   | -   | 0.2  | Vdc        |
| Output Voltage (off)<br>( $V_{CC} = 5.0\text{ V}$ , $V_B = 0.25\text{ V}$ , $R_L = 1.0\text{ k}\Omega$ ) | $V_{OH}$      | 4.9 | -   | -    | Vdc        |
| Input Resistor   | R1            | 70  | 100 | 130  | k $\Omega$ |
| Resistor Ratio   | $R_1/R_2$     | 0.8 | 1.0 | 1.2  |            |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle  $\leq$  2%.

TYPICAL CHARACTERISTICS  
 MUN2236, MMUN2236L, MUN5236, NSVMUN5236, DTC115EE, DTC115EM3

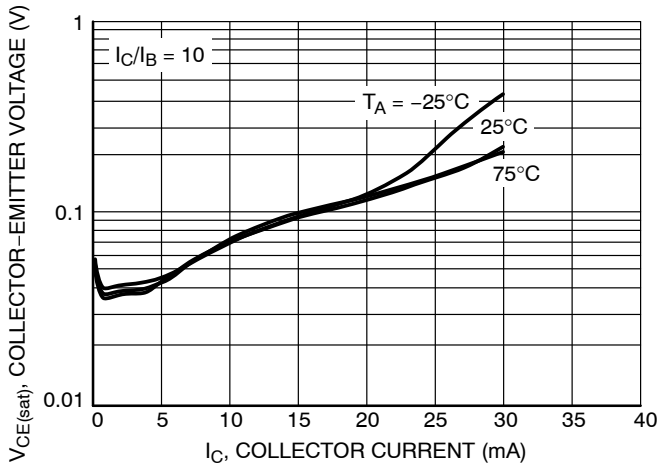


Figure 2.  $V_{CE(sat)}$  versus  $I_C$

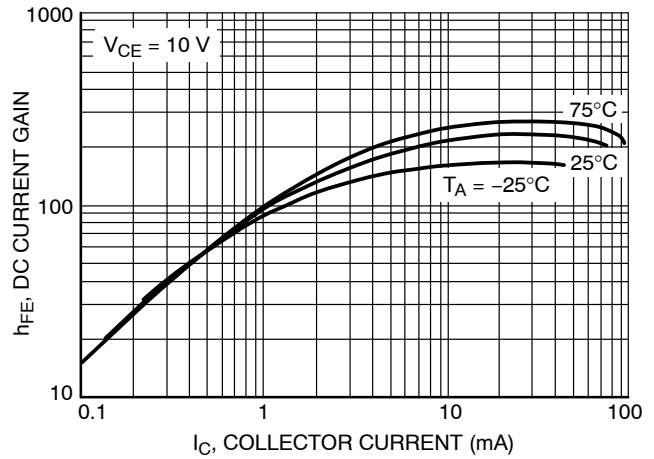


Figure 3. DC Current Gain

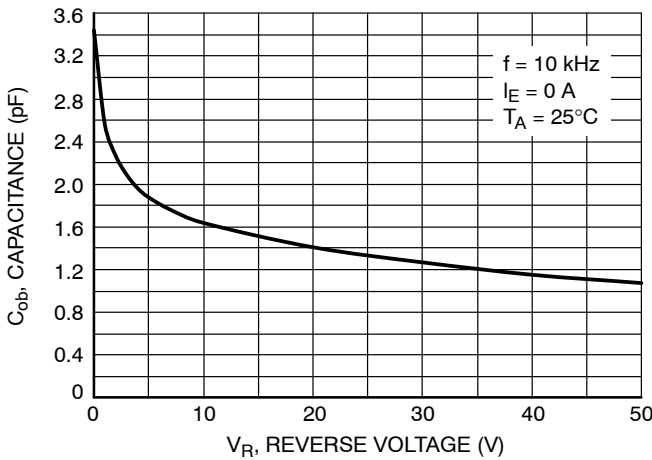


Figure 4. Output Capacitance

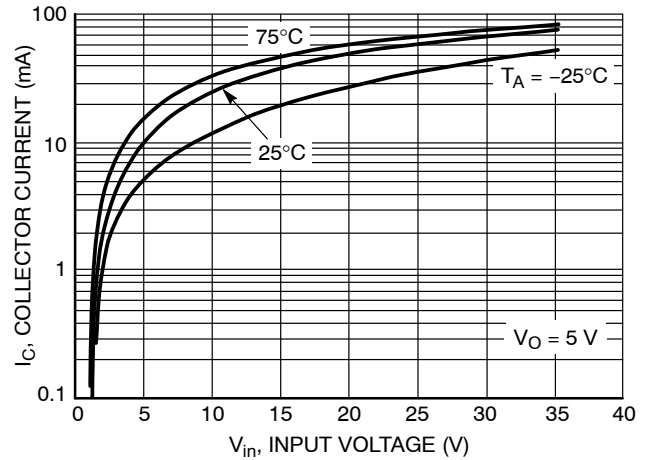


Figure 5. Output Current versus Input Voltage

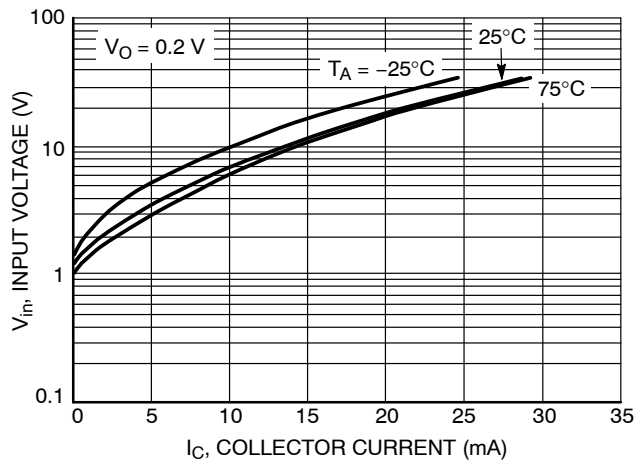
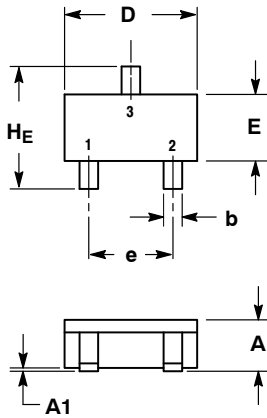


Figure 6. Input Voltage versus Output Current

PACKAGE DIMENSIONS

SC-59  
CASE 318D-04  
ISSUE H

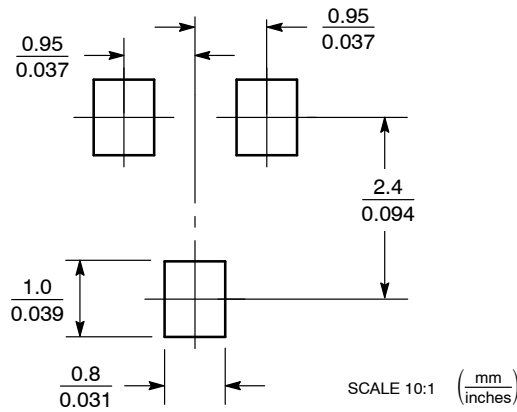


NOTES:  
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
2. CONTROLLING DIMENSION: MILLIMETER.

| DIM | MILLIMETERS |      |      | INCHES |       |       |
|-----|-------------|------|------|--------|-------|-------|
|     | MIN         | NOM  | MAX  | MIN    | NOM   | MAX   |
| A   | 1.00        | 1.15 | 1.30 | 0.039  | 0.045 | 0.051 |
| A1  | 0.01        | 0.06 | 0.10 | 0.001  | 0.002 | 0.004 |
| b   | 0.35        | 0.43 | 0.50 | 0.014  | 0.017 | 0.020 |
| c   | 0.09        | 0.14 | 0.18 | 0.003  | 0.005 | 0.007 |
| D   | 2.70        | 2.90 | 3.10 | 0.106  | 0.114 | 0.122 |
| E   | 1.30        | 1.50 | 1.70 | 0.051  | 0.059 | 0.067 |
| e   | 1.70        | 1.90 | 2.10 | 0.067  | 0.075 | 0.083 |
| L   | 0.20        | 0.40 | 0.60 | 0.008  | 0.016 | 0.024 |
| HE  | 2.50        | 2.80 | 3.00 | 0.099  | 0.110 | 0.118 |

STYLE 1:  
PIN 1. BASE  
2. EMITTER  
3. COLLECTOR

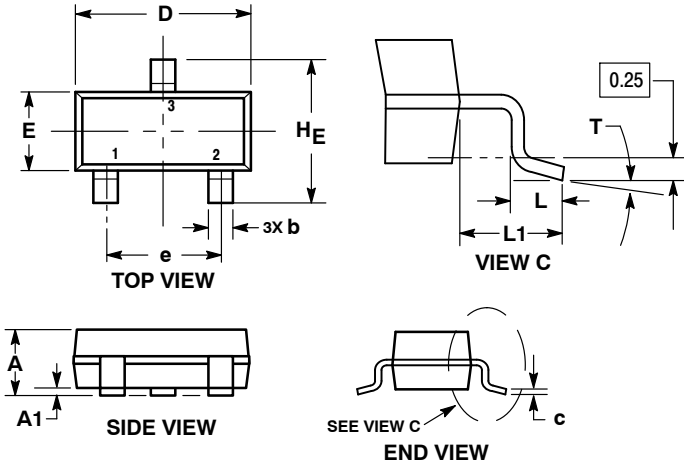
SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-23 (TO-236)  
CASE 318-08  
ISSUE AS

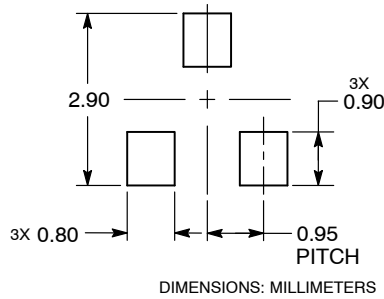


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS |      |      | INCHES |       |       |
|-----|-------------|------|------|--------|-------|-------|
|     | MIN         | NOM  | MAX  | MIN    | NOM   | MAX   |
| A   | 0.89        | 1.00 | 1.11 | 0.035  | 0.039 | 0.044 |
| A1  | 0.01        | 0.06 | 0.10 | 0.000  | 0.002 | 0.004 |
| b   | 0.37        | 0.44 | 0.50 | 0.015  | 0.017 | 0.020 |
| c   | 0.08        | 0.14 | 0.20 | 0.003  | 0.006 | 0.008 |
| D   | 2.80        | 2.90 | 3.04 | 0.110  | 0.114 | 0.120 |
| E   | 1.20        | 1.30 | 1.40 | 0.047  | 0.051 | 0.055 |
| e   | 1.78        | 1.90 | 2.04 | 0.070  | 0.075 | 0.080 |
| L   | 0.30        | 0.43 | 0.55 | 0.012  | 0.017 | 0.022 |
| L1  | 0.35        | 0.54 | 0.69 | 0.014  | 0.021 | 0.027 |
| HE  | 2.10        | 2.40 | 2.64 | 0.083  | 0.094 | 0.104 |
| T   | 0°          | ---  | 10°  | 0°     | ---   | 10°   |

STYLE 6:  
PIN 1. BASE  
2. EMITTER  
3. COLLECTOR

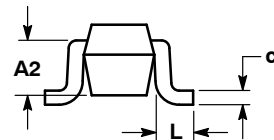
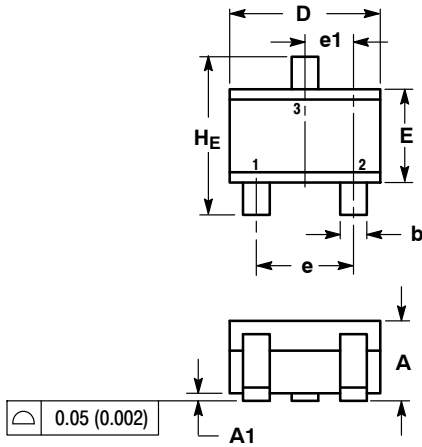
RECOMMENDED  
SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SC-70 (SOT-323)  
CASE 419-04  
ISSUE N



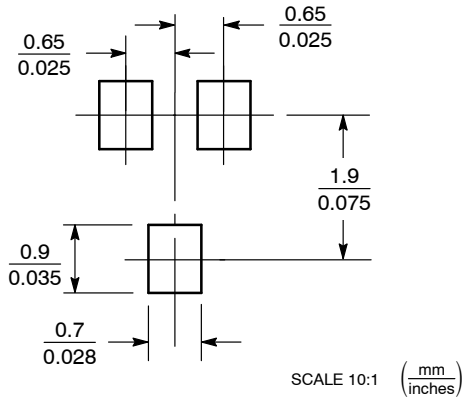
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

| DIM | MILLIMETERS |      |      | INCHES    |       |       |
|-----|-------------|------|------|-----------|-------|-------|
|     | MIN         | NOM  | MAX  | MIN       | NOM   | MAX   |
| A   | 0.80        | 0.90 | 1.00 | 0.032     | 0.035 | 0.040 |
| A1  | 0.00        | 0.05 | 0.10 | 0.000     | 0.002 | 0.004 |
| A2  | 0.70 REF    |      |      | 0.028 REF |       |       |
| b   | 0.30        | 0.35 | 0.40 | 0.012     | 0.014 | 0.016 |
| c   | 0.10        | 0.18 | 0.25 | 0.004     | 0.007 | 0.010 |
| D   | 1.80        | 2.10 | 2.20 | 0.071     | 0.083 | 0.087 |
| E   | 1.15        | 1.24 | 1.35 | 0.045     | 0.049 | 0.053 |
| e   | 1.20        | 1.30 | 1.40 | 0.047     | 0.051 | 0.055 |
| e1  | 0.65 BSC    |      |      | 0.026 BSC |       |       |
| L   | 0.20        | 0.38 | 0.56 | 0.008     | 0.015 | 0.022 |
| HE  | 2.00        | 2.10 | 2.40 | 0.079     | 0.083 | 0.095 |

STYLE 3:  
PIN 1. BASE  
2. EMITTER  
3. COLLECTOR

SOLDERING FOOTPRINT\*

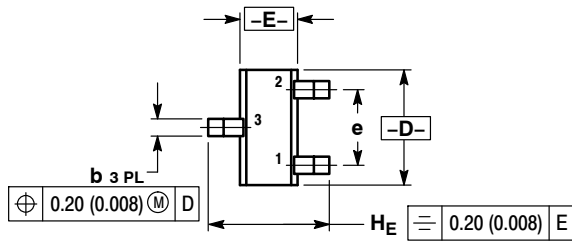


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



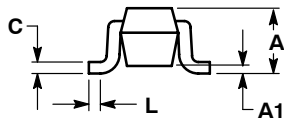
PACKAGE DIMENSIONS

SC-75/SOT-416  
CASE 463  
ISSUE G



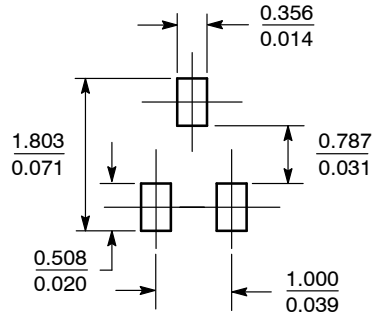
- NOTES:  
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
2. CONTROLLING DIMENSION: MILLIMETER.

| DIM            | MILLIMETERS |      |      | INCHES   |       |       |
|----------------|-------------|------|------|----------|-------|-------|
|                | MIN         | NOM  | MAX  | MIN      | NOM   | MAX   |
| A              | 0.70        | 0.80 | 0.90 | 0.027    | 0.031 | 0.035 |
| A1             | 0.00        | 0.05 | 0.10 | 0.000    | 0.002 | 0.004 |
| b              | 0.15        | 0.20 | 0.30 | 0.006    | 0.008 | 0.012 |
| C              | 0.10        | 0.15 | 0.25 | 0.004    | 0.006 | 0.010 |
| D              | 1.55        | 1.60 | 1.65 | 0.061    | 0.063 | 0.065 |
| E              | 0.70        | 0.80 | 0.90 | 0.027    | 0.031 | 0.035 |
| e              | 1.00 BSC    |      |      | 0.04 BSC |       |       |
| L              | 0.10        | 0.15 | 0.20 | 0.004    | 0.006 | 0.008 |
| H <sub>E</sub> | 1.50        | 1.60 | 1.70 | 0.060    | 0.063 | 0.067 |



- STYLE 1:  
PIN 1. BASE  
2. EMITTER  
3. COLLECTOR

SOLDERING FOOTPRINT\*



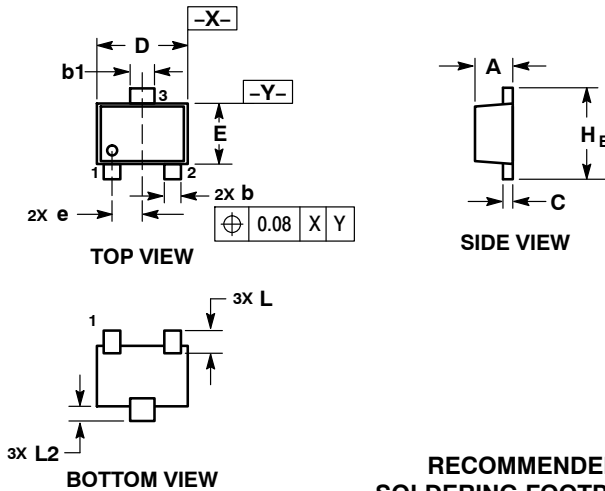
SCALE 10:1 ( $\frac{\text{mm}}{\text{inches}}$ )

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MUN2236, MMUN2236L, MUN5236, DTC115EE, DTC115EM3

## PACKAGE DIMENSIONS

### SOT-723 CASE 631AA ISSUE D



#### NOTES:

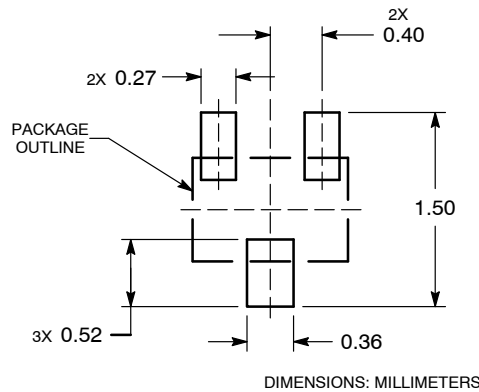
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

| DIM | MILLIMETERS |      |      |
|-----|-------------|------|------|
|     | MIN         | NOM  | MAX  |
| A   | 0.45        | 0.50 | 0.55 |
| b   | 0.15        | 0.21 | 0.27 |
| b1  | 0.25        | 0.31 | 0.37 |
| C   | 0.07        | 0.12 | 0.17 |
| D   | 1.15        | 1.20 | 1.25 |
| E   | 0.75        | 0.80 | 0.85 |
| e   | 0.40 BSC    |      |      |
| H E | 1.15        | 1.20 | 1.25 |
| L   | 0.29 REF    |      |      |
| L2  | 0.15        | 0.20 | 0.25 |

#### STYLE 1:

1. BASE
2. EMITTER
3. COLLECTOR

### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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